

[Document Name] Abstract

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[Problem] According to the present invention, it is made possible to form a multi-layered circuit pattern with a high accuracy of overlaying and a high productivity, even in the formation of a minute circuit pattern with a high density.

[Solution] An overlay mark for use in the measurement of overlay accuracy and the alignment in light exposure of laminated patterns, wherein a mark pattern is formed by engraving a groove or an indent at a prescribed position on a layer on which a circuit pattern is to be formed, and

a groove pattern is formed on the same layer so that the mark pattern is enclosed and prevented from deformation owing to the thermal expansion or contraction of the layer.

[Selected Drawing] Fig. 1